TEI0001 TRM

Download PDF version of this document.

Table of Contents

Overview

The Trenz Electronic TEI0001 MAX1000 is a low cost small-sized FPGA module integrating a Intel MAX 10 FPGA SoC, 8 MByte serial memory for user application, 8 MByte SDRAM and a 3-axis accelerometer.

Key Features

- Intel MAX 10 10M08 FPGA SoC
- 8 MByte SDRAM
- 8 MByte QSPI Flash memory
- ST Microelectronics LIS3DH 3-axis accelerometer
- JTAG and UART over Micro USB2 connector
- 1x6 pin header for JTAG access to FPGA SoC

- 1x PMOD header providing 8 GPIOs
- 2x 14-pin headers (2,54 mm pitch) providing 22 GPIOs with 7 analog inputs as alternative function
- 1x 3-pin header providing 2 analog inputs or 1 GPIO
- 8x user LEDs
- 1x user push button
- 5.0V single power supply with on-board voltage regulators
- Size: 61.5 x 25 mm

Additional assembly options are available for cost or performance optimization upon request.

Block Diagram

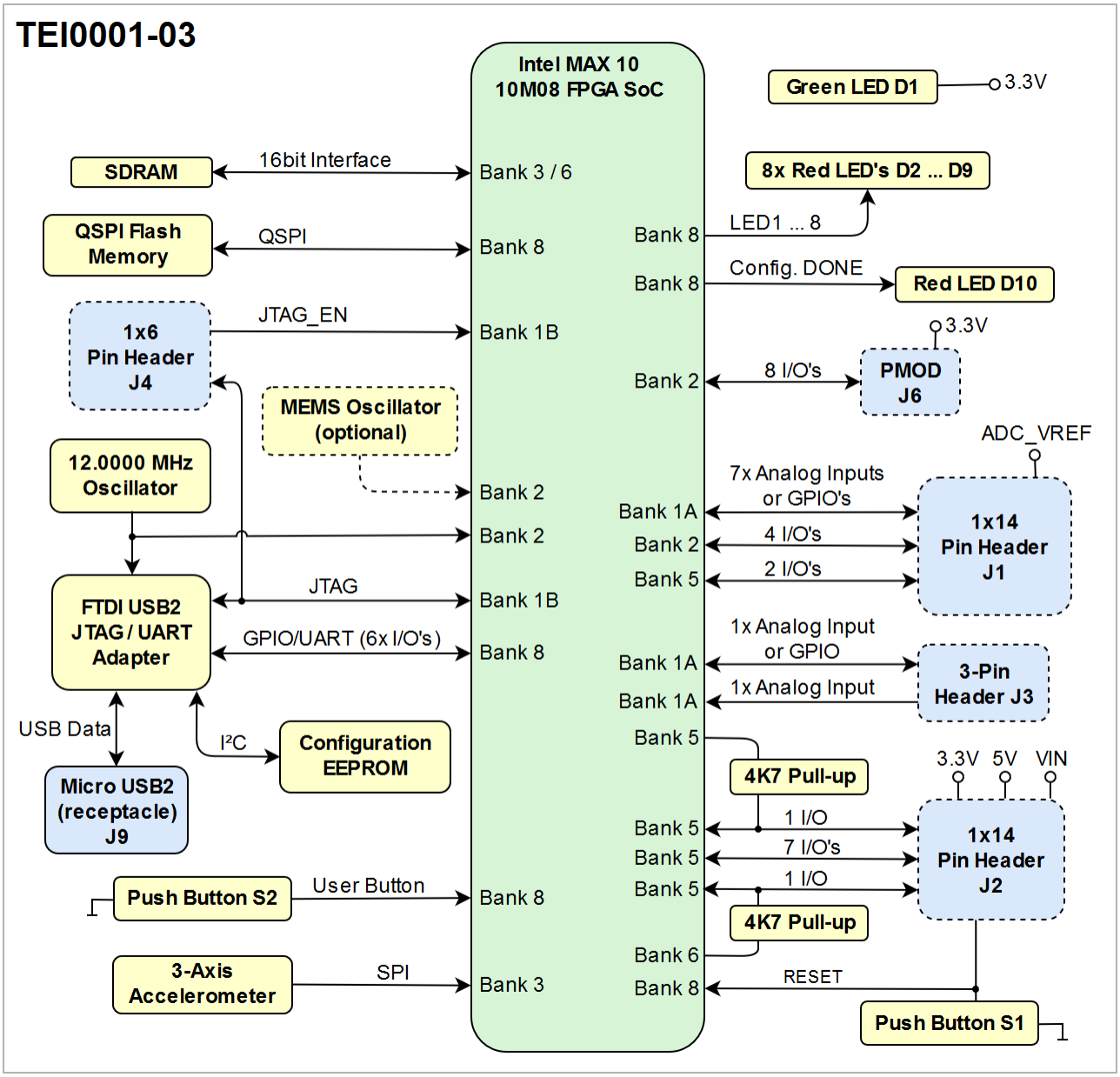

Figure 1: TEI0003-02 block diagram

Main Components

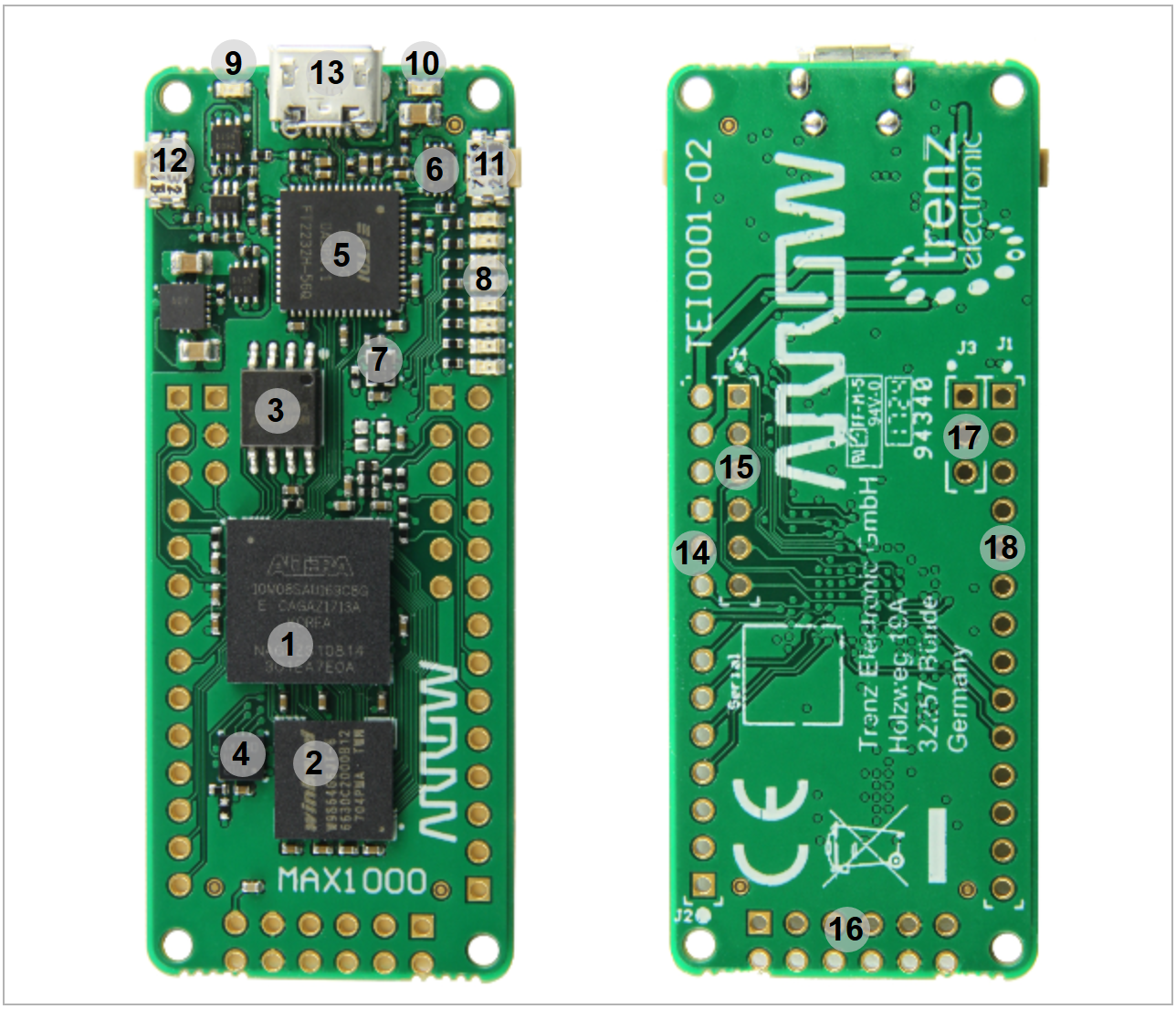

Figure 2: TEI0003-02 FPGA module

1. Intel MAX 10 10M08 FPGA SoC, U1
2. 8 Mbyte SDRAM 166MHz, U2
3. 8 Mbyte QSPI Flash memory, U5
4. ST Microelectronics LIS3DH 3-axis accelerometer, U4
5. FTDI USB2 to JTAG/UART adapter, U3
6. Configuration EEPROM for FTDI chip, U9
7. 12.0000 MHz oscillator, U7
8. 8x red user LEDs, D2 ... D9
9. Red LED (Conf. DONE), D10
10. Green LED (indicating supply voltage), D1
11. Push button (user), S2
12. Push button (reset), S1
13. Micro USB2 B socket (receptacle), J9

14. 1x14 pin header (2.54mm pitch), J2
15. 1x6 pin header (2.54mm pitch), J4
16. 2x6 Pmod connector, J6
17. 3-pin header (2.54mm pitch), J3
18. 1x14 pin header (2.54mm pitch), J1

Initial Delivery State

Storage device name	Content	Notes
Quad SPI Flash, U5	DEMO Design	-
I^2C Configuration EEPROM, U9	Programmed	-

Table 1: Initial delivery state of programmable devices on the module

Boot Process

The FPGA configuration for Intel MAX 10 FPGAs can be stored through JTAG interface on the FPGA itself since the Intel MAX 10 FPGA offers non-volatile memory on chip. The FPGA configuration is loaded from the non-volatile memory when the board is powered up.

To configure the FPGA directly, the JTAG interface can be used to configure the FPGA volatile, means the configuration is lost after power off.

Signals, Interfaces and Pins

I/Os on Pin Headers and Connectors

I/O signals of the FPGA SoC's I/O banks connected to the board's pin headers and connectors:

Bank	Connector Designator	I/O Signal Count	Bank Voltage	Notes
2	J1	4 I/O's	3.3V	-
	J6	8 I/O's		Pmod connector
5	J1	2 I/O's	3.3V	-
	J2	9 I/O's		2 I/O's of bank 5 can be pulled-up to 3.3V (4K7 resistors)
1A	J1	7x analog inputs or GPIO's, 1x Analog reference voltage (AREF)	3.3V	analog pins usable as GPIO's as alternative function
	J3	1x analog inputs or GPIO, 1x dedicated analog input		
1B	J4	JTAG interface and 'JTAGEN' signal (5 I/O's)	3.3V	JTAG enable signal (JTAGEN) on pin J4-2, switch between user I/O pins and JTAG pin functions

Table 2: General overview of single ended I/O signals connected to pin headers and connectors

FPGA I/O banks

Table below contains the signals and interfaces of the FPGA banks connected to pins and peripherals of the board:

Bank	I/O's Count	Connected to	Notes

2	4	1x14 pin header, J1	user GPIO's
	8	Pmod connector, J6	user GPIO's
	1	clock oscillator, U7	12.0000 MHz reference clock input
	1	optional clock oscillator, U6	oscillator not fitted, footprints available for Microchip MEMS oscillator
5	9	1x14 pin header, J2	2 I/O's (D11, D12) of bank 5 can be pulled-up to 3.3V (4K7 resistors) with 1 I/O (D12_R) of same Bank and 1 I/O (D11_R) of bank 6
6	18	8 MByte SDRAM 166MHz, U2	16bit SDRAM memory interface
3	22	8 MByte SDRAM 166MHz, U2	16bit SDRAM memory interface
	6	LIS3DH 3-axis accelerometer, U4	4 I/O's for SPI interface, 2 interrupt lines
1A	8	1x14 pin headers J1	7 analog inputs or GPIO's, 1 pin analog reference voltage input
	2	pin headers J1	1 analog inputs or GPIO, 1 dedicated analog input
1B	5	pin header J4	4 I/O's JTAG interface and 1x 'JTAGEN' signal to switch the JTAG pins to user GPIO's if drive this pin to GND
8	8	LEDs D2 ... D9	Red user LEDs
	6	QSPI Flash memory, U5	6 pins Quad SPI interface, 2 of them pulled up as configuration pins during initialization
	6	FTDI FT2232H JTAG/UART Adapter, U3	6 pins configurable as GPIO/UART or other serial interfaces
	1	Red LED, D10	Configuration DONE Led (ON when configuration in progress, OFF when configuration is done)
	1	User button S2	user configurable
	1	Reset button S1 and pin J2-10	low active reset line for FPGA reconfiguration

Table 3: General overview of FPGA I/O banks

JTAG Interface

Primary JTAG access to the FPGA SoC device U1 is provided through Micro USB2 B connector J9. The JTAG interface is created by the FTDI FT2232H USB2 to JTAG/UART adapter IC U3.

Optionally 1x6 male pin header J4 can be fitted on board for access to the JTAG interface between FTDI and FPGA on board. The pin assignment of header J4 is shown on table below:

JTAG Signal	Pin on Header J4	Note
TCK	3	-
TDI	5	-
TDO	4	-
TMS	6	-
JTAGEN	2	leave floating when use JTAG interface, otherwise signals on FPGA are GPIOs

Table 4: optional JTAG pin header

On-board Peripherals

Serial Configuration Memory

On-board serial configuration memory (U5) is provided by Winbond W74M64FVSSIQ with 64 MBit (8 MByte) storage capacity. This non volatile memory is used to store initial FPGA configuration via JTAG interface. The memory is connected to FPGA bank 1 via SPI interface.

Serial Memory U5 Pin	Signal Schematic Name	Connected to	Notes
Pin 1, CS	F_CS	FPGA bank 8, pin B3	chip select
Pin 6, CLK	F_CLK	FPGA bank 8, pin A3	clock
Pin 5, SI/IO0	F_DI	FPGA bank 8, pin A2	data in / out
Pin 7, HOLD/IO3	NSTATUS	FPGA bank 8, pin C4	data in / out, configuration dual-purpose pin of FPGA
Pin 3, WP/IO2	DEVCLRN	FPGA bank 8, pin B9	data in / out, configuration dual-purpose pin of FPGA
Pin 2, SO/IO1	F_DO	FPGA bank 8, pin B2	data in / out

Table 5: Quad SPI Flash memory interface

SDRAM

The FPGA module is equipped with a Winbond W9864G6JT 64 MBit (8 MByte) SDRAM chip U2 in standard configuration, variants with 256 Mbit (32 MByte) memory density are also available. The SDRAM chip is connected to the FPGA bank 3 and 6 via 16-bit memory interface with 166MHz clock frequency and CL3 CAS latency.

SDRAM I/O Signals	Signal Schematic Name	Connected to	Notes
Address inputs	A0 ... A13	bank 3	-
Bank address inputs	BA0 / BA1	bank 3	-
Data input/output	DQ0 ... DQ15	bank 6	-
Data mask	DQM0 ... DQM1	bank 6	-
Clock	CLK	bank 3	
Control Signals	CS	bank 3	Chip select
	CKE	bank 3	Clock enable
	RAS	bank 3	Row Address Strobe
	CAS	bank 3	Column Address Strobe
	WE	bank 3	Write Enable

Table 6: 16bit SDRAM memory interface

FTDI FT2232H Chip

The FTDI chip U3 converts signals from USB2 to a variety of standard serial and parallel interfaces. Refer to the FTDI data sheet to get information about the capacity of the FT2232H chip.
FTDI FT2232H chip is used in MPPSE mode for JTAG, 6 I/O's of Channel B are routed to FPGA bank 8 of the FPGA SoC and are usable for example as GPIOs, UART or other standard interfaces.

The configuration of FTDI FT2232H chip is pre-programmed on the EEPROM U9.

FTDI Chip U3 Pin	Signal Schematic Name	Connected to	Notes
Pin 12, ADBUS0	TCK	FPGA bank 1B, pin G2	JTAG interface
Pin 13, ADBUS1	TDI	FPGA bank 1B, pin F5	
Pin 14, ADBUS2	TDO	FPGA bank 1B, pin F6	
Pin 15, ADBUS3	TMS	FPGA bank 1B, pin G1	

Pin 32, BDBUS0	BDBUS0	FPGA bank 8, pin A4	user configurable
Pin 33, BDBUS1	BDBUS1	FPGA bank 8, pin B4	user configurable
Pin 34, BDBUS2	BDBUS2	FPGA bank 8, pin B5	user configurable
Pin 35, BDBUS3	BDBUS3	FPGA bank 8, pin A6	user configurable
Pin 37, BDBUS4	BDBUS4	FPGA bank 8, pin B6	user configurable
Pin 38, BDBUS5	BDBUS5	FPGA bank 8, pin A7	user configurable

Table 7: FTDI chip interfaces and pins

3-Axis Accelerometer

On the TEI0001 FPGA board there is a 3-axis accelerometer present. This accelerometer provided by ST Microelectronics LIS3DH and offers many function to detect motion and has also a temperature sensor integrated. It also has a FIFO buffer for storing output data. The sensor is connected to the FPGA through SPI interface and two interrupt lines.

Accelerometer U4 Pin	Signal Schematic Name	Connected to	Notes
Pin 11, INT1	SEN_INT1	FPGA bank 3, pin J5	Interrupt lines
Pin 9, INT2	SEN_INT2	FPGA bank 3, pin L4	
Pin 6, SDA/SDI/SDO	SEN_SDI	FPGA bank 3, pin J7	SPI interface
Pin 7, SDO/SA0	SEN_SDO	FPGA bank 3, pin K5	
Pin 4, SCL/SPC	SEN_SPC	FPGA bank 3, pin J6	
Pin 8, CS	SEN_CS	FPGA bank 3, pin L5	
Pin 13, ADC3	ADC3	5V	Sense 5V input voltage

Table 8: 3-axis accelerometer interfaces and pins

System Clock Oscillator

The FPGA SoC module has following reference clocking signals provided by on-board oscillators:

Clock Source	Schematic Name	Frequency	Clock Input Destination
Microchip MEMS Oscillator, U7	CLK12M	12.0000 MHz	FTDI FT2232 U3, pin 3; FPGA SoC bank 2, pin H6
optional Microchip MEMS Oscillator, U6 (not fitted)	CLK_X	-	FPGA SoC bank 2, pin G5

Table 9: Clock sources overview

On-board LEDs

There are 10 LEDs fitted on the FPGA module board. The LEDs are user configurable to indicate for example any system status.

LED	Color	Signal Schematic Name	FPGA	Notes
D1	Green	-	-	Indicating 3.3V board supply voltage
D2	Red	'LED1'	bank 8, pin A8	user
D3	Red	'LED2'	bank 8, pin A9	user
D4	Red	'LED3'	bank 8, pin A11	user
D5	Red	'LED4'	bank 8, pin A10	user

D6	Red	'LED5'	bank 8, pin B10	user
D7	Red	'LED6'	bank 8, pin C9	user
D8	Red	'LED7'	bank 8, pin C10	user
D9	Red	'LED8'	bank 8, pin D8	user
D10	Red	'CONF_DONE'	bank 8, pin C5	indication configuration is DONE when LED is off

Table 10: LEDs of the module

Push Buttons

The FPGA module is equipped with two push buttons S1 and S2:

Button	Signal Schematic Name	FPGA	Notes
S1	'USER_BTN'	bank 8, pin E6	user configurable
S2	'RESET'	bank 8, pin E7	FPGA reset

Table 11: Push buttons of the module

Connectors

All connectors are are for 100mil headers, all connector locations are in 100mil (2.54mm) grid. The module's PCB provides footprints to mount and solder optional pin headers, if those are not factory-fitted on module.

Power and Power-On Sequence

To power-up a module, power supply with minimum current capability of 1A is recommended.

Power Supply

The FPGA module can be power-supplied through Micro USB2 connector J9 with supply voltage 'USB-VBUS' or alternative through pin header J2 with supply voltage 'VIN'.

The TEI0001 module needs one single power supply of 5.0V nominal.

There are following dependencies how the initial voltage of the extern power supply is distributed to the on-board DCDC converters:

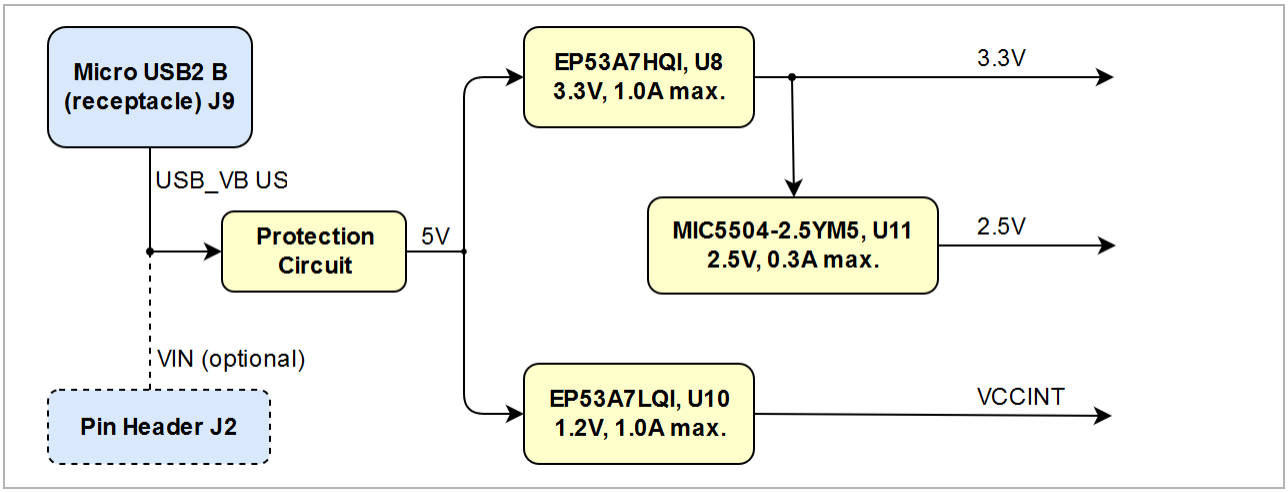

Figure 3: Power Distribution Diagram

Power Consumption

FPGA	Design	Typical Power, 25C ambient
Intel MAX 10 10M08 FPGA SoC	Not configured	TBD*

Table 12: Module power consumption

*TBD - To Be Determined.

Actual power consumption depends on the FPGA design and ambient temperature.

Power-On Sequence

There is no specific or special power-on sequence, just one single power source is needed.

Power Rails

Connector Designator	VCC / VCCIO Schematic Name	Voltage	Direction	Pins	Notes
J2	5V	5.0V	Out	Pin 14	-
	VIN	5.0V	In	Pin 13	-
	3.3V	3.3V	Out	Pin 12	-
J6	3.3V	3.3V	Out	Pin 6, 12	-
J9	USB_VBUS	5.0V	In	Pin 1	-

Table 13: Connector power pin description

Bank Voltages

Bank	Voltage	Voltage Range
2	3.3V	all bank voltages fixed

3	3.3V
5	3.3V
6	3.3V
1A	3.3V
1B	3.3V
8	3.3V

Table 14: FPGA SoC VCCO bank voltages

Technical Specifications

Absolute Maximum Ratings

Parameter	Min	Max	Units	Reference document
VIN supply voltage (5.0V nominal)	-0.3	6.0	V	EP53A7HQI datasheet
I/O Input voltage for FPGA I/O bank	-0.5	4.12	V	Intel MAX 10 datasheet
Storage Temperature	-40	+90	°C	LED R6C-AL1M2VY/3T datasheet

Table 15: Absolute maximum ratings

Recommended Operating Conditions

Parameter	Min	Max	Units	Reference document
VIN supply voltage (5.0V nominal)	4.75	5.25	V	same as USB-VBUS specification
I/O Input voltage for FPGA I/O bank	–0.5	3.6	V	Intel MAX 10 datasheet
Operating temperature range	0	+70	°C	Winbond datasheet W9864G6GT

Table 16: Recommended operating conditions

⚠ Please check Intel MAX 10 datasheet for complete list of absolute maximum and recommended operating ratings for the FPGA device.

Physical Dimensions

- Board size: PCB 25mm × 61,5mm. Notice that some parts the are hanging slightly over the edge of the PCB like the the Micro USB2 B connector, which determine the total physical dimensions of the carrier board. Please download the assembly diagram for exact numbers.
- PCB thickness: ca. 1.65mm
- Highest part on the PCB without fitted headers and connectors is the Micro USB2 B connector, which has an approximately hight of 3 mm. Please download the step model for exact numbers.

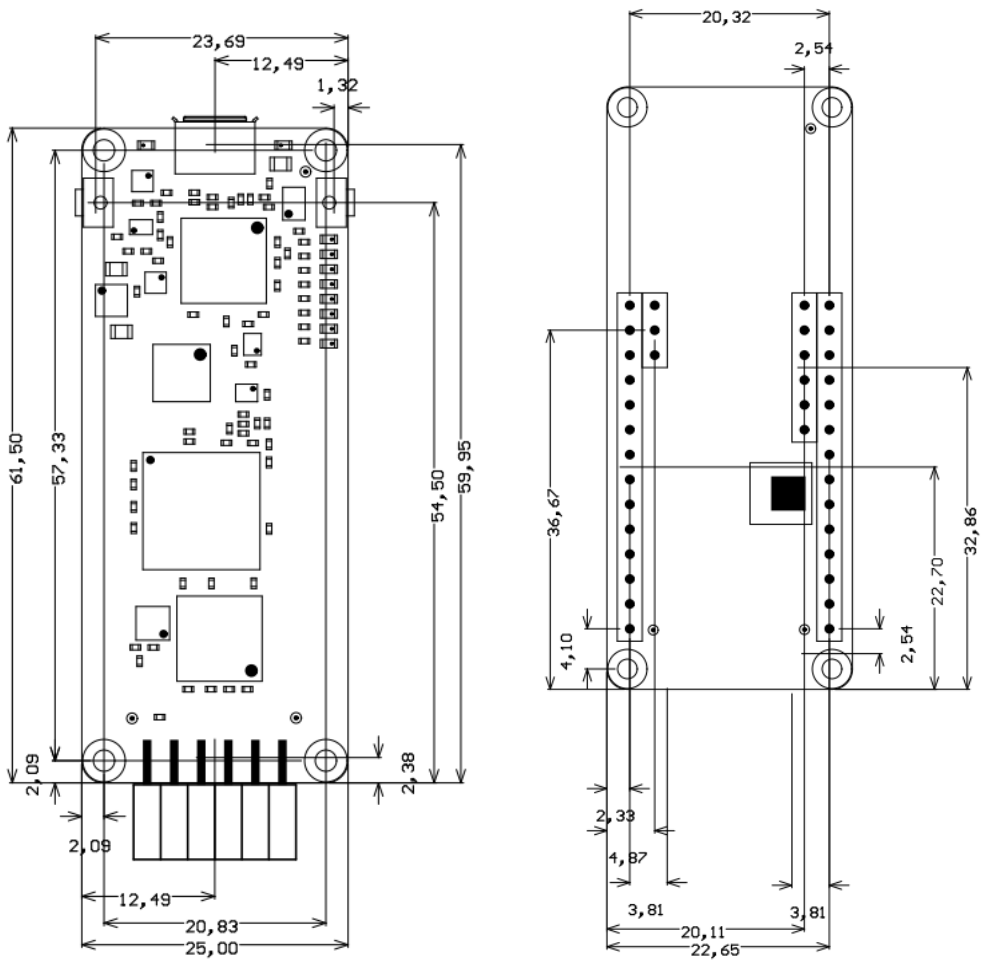

Figure 4: Module physical dimensions drawing

Revision History

Hardware Revision History

Date	Revision	Notes	PCN	Documentation Link
-	03	Current available revision	-	TEI0001-03
-	02	First Production Release	-	TEI0001-02
-	01	Prototypes	-	TEI0001-01

Table 17: Module hardware revision history

Hardware revision number is printed on the PCB board together with the module model number separated by the dash.

Figure 5: Module hardware revision number

Document Change History

Date	Revision	Contributors	Description
Error rendering macro 'page-info' Ambiguous method overloading for method jdk.proxy279.$Proxy4022#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	**Error rendering macro 'page-info'** Ambiguous method overloading for method jdk.proxy279.$Proxy4022#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] Unknown macro: 'metadata'	Ali Naseri	• small corrections
2018-06-29	v.17	Ali Naseri	• First TRM release

Table 18: Document change history

Disclaimer

Data Privacy

Please also note our data protection declaration at https://www.trenz-electronic.de/en/Data-protection-Privacy

Document Warranty

The material contained in this document is provided “as is” and is subject to being changed at any time without notice. Trenz Electronic does not warrant the accuracy and completeness of the materials in this document. Further, to the maximum extent permitted by applicable law, Trenz Electronic disclaims all warranties, either express or implied, with regard to this document and any information contained herein, including but not limited to the implied warranties of merchantability, fitness for a particular purpose or non infringement of intellectual property. Trenz Electronic shall not be liable for errors or for incidental or consequential damages in connection with the furnishing, use, or performance of this document or of any information contained herein.

Limitation of Liability

In no event will Trenz Electronic, its suppliers, or other third parties mentioned in this document be liable for any damages whatsoever (including, without limitation, those resulting from lost profits, lost data or business interruption) arising out of the use, inability to use, or the results of use of this document, any documents linked to this document, or the materials or information contained at any or all such documents. If your use of the materials or information from this document results in the need for servicing, repair or correction of equipment or data, you assume all costs thereof.

Copyright Notice

Technology Licenses

The hardware / firmware / software described in this document are furnished under a license and may be used /modified / copied only in accordance with the terms of such license.

Environmental Protection

To confront directly with the responsibility toward the environment, the global community and eventually also oneself. Such a resolution should be integral part not only of everybody's life. Also enterprises shall be conscious of their social responsibility and contribute to the preservation of our common living space. That is why Trenz Electronic invests in the protection of our Environment.

REACH, RoHS and WEEE

REACH

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of REACH. The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no SVHC (Substances of Very High Concern) on the Candidate List are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA).

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

Error rendering macro 'page-info'

Ambiguous method overloading for method jdk.proxy279.$Proxy4022#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]